

SH Series



Agency Approvals

Agency	Agency File Number
	E128662

Two Electrode GDT Graphical Symbol



Additional Information



Datasheet



Resources



Samples

Description

The Littelfuse SH Gas Discharge Tubes (GDT) series provides high levels of protection against fast rising transients caused by lightning disturbances. It has a surge rating of 5kA, 8/20 μ s. Offered in a Squared Surface Mount package, which helps to make pick and place on PCB process easier.

This GDT series is perfectly suited for broadband equipment applications. The GDT's low off-state capacitance is compatible with high bandwidth applications and this capacitance loading value does not vary if the voltage across the GDT changes.

The Littelfuse SH Gas Discharge Tube (GDT) series are specifically designed for protection of electrical, multimedia, and communication equipment against over voltage transients in surface mount assembly applications.

Features

- Excellent response to fast rising transients
- GHz working frequency
- 5kA, 8/20 μ s surge capability as defined by IEC 61000-4-5 2nd Edition
- UL recognized
- Offered with squared body package
- Non-Radioactive
- Ultra Low capacitance (<0.7pF)
- Lead-free and RoHS compliant

Applications

- CATV equipment
- Antennas
- RS 485
- Telecom Base Station
- Power Supply AC Main
- G.fast
- EV power Charging
- Inverter/Variable Frequency Drivers (VFDs)
- IEEE 802.3 compliant Ethernet interfaces
- Broad Band equipment
- xDSL, ADSL, ADSL2, VDSL, and VDSL2
- Medical Electronics
- Test Equipment
- General Telecom Equipment
- Renewable Energy

Electrical Characteristics

Part Number	Component Specifications (at 25°C)							Life Ratings					
	DC Breakdown in Volts (@100V/s)			Maximum Impulse Break-down Voltage		Maximum Impulse Discharge Current (8/20µs)	Insulation Resistance	Capacitance (@1MHz)	Impulse Discharge Current (8/20µs)	AC Discharge Current (50Hz, 1sec)	AC Discharge Current (9 Cycles @50Hz)	DC Holdover Voltage (<150ms)*	Impulse Life (10/1000µs (100A)
	MIN	TYP	MAX	@100V/µs	1000V/µs	1 Time	MIN	MAX	MAX	MIN	MIN		MIN
SH75	60	75	90	600	700	6kA	1GΩ @50V	0.7pf	10 Shots @ (5kA) 1 Shot at 6kA**	5A	15A		300 Shots
SH90	72	90	108	600	700								
SH145	116	145	174	600	700								
SH230	186	230	276	600	700								
SH250	200	250	300	600	700								
SH300	240	300	360	650	800								
SH350	280	350	420	750	900								
SH400	360	400	480	850	1000								
SH470	376	470	564	900	1100								
SH600	480	600	720	1000	1200								

Note:

* Reference REA PE-80, 0.2A, tested to ITU-T Rec K.12 and REA PE 80 <150 ms.

** DC spark-over may exceed ± 25% after discharge, but will continue to protect without venting

Product Characteristics

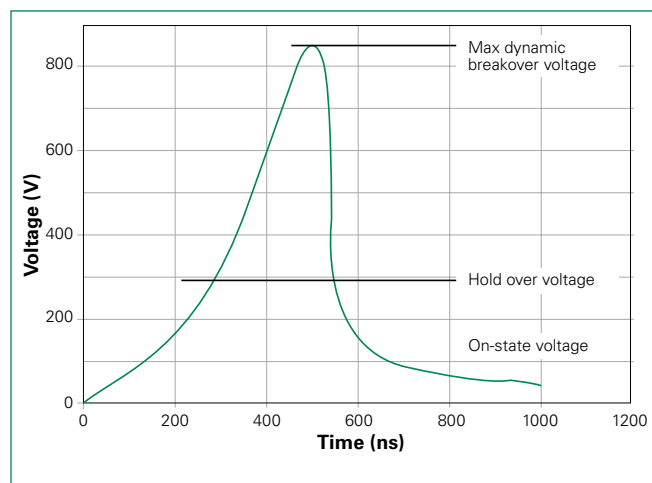
Materials	Device Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator
Storage and Operational Temperature	-40 to +90°C

Typical Insertion Loss

@1.0GHz = 0.08dB
@1.4GHz = 0.16dB
@1.8GHz = 0.26dB
@2.0GHz = 0.33dB
@2.4GHz = 0.47dB
@2.8GHz = 0.59dB
@3.1GHz = 0.70dB
@3.5GHz = 0.89dB
@4.0GHz = 1.24dB

Note: Insertion data for customer reference only, application testing needed for verification.

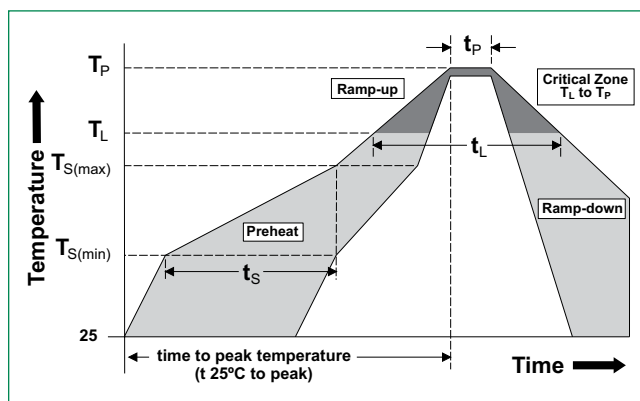
Voltage Vs. Time Characteristic



Note: Tested per 1kV/µs waveform

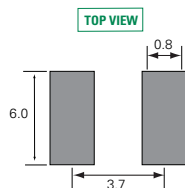
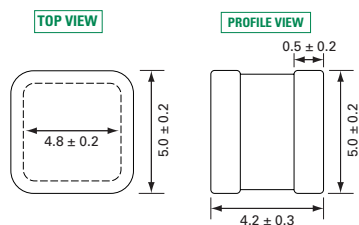
Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_p)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



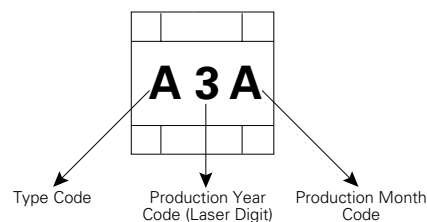
Product Dimensions

Dimensions in millimeters



Recommended Soldering Pad Layout

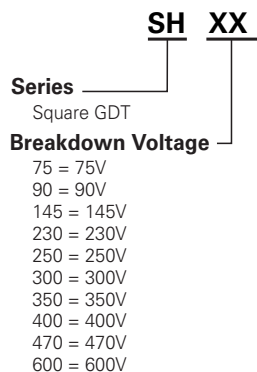
Product Marking



Type Code	
A	SH75
B	SH90
S	SH145
D	SH230
R	SH250
E	SH300
G	SH350
I	SH400
P	SH470
V	SH600

Month Code	
A	January
B	February
C	March
D	April
E	May
F	June
G	July
H	August
I	September
J	October
K	November
L	December

Part Numbering System and Ordering Information

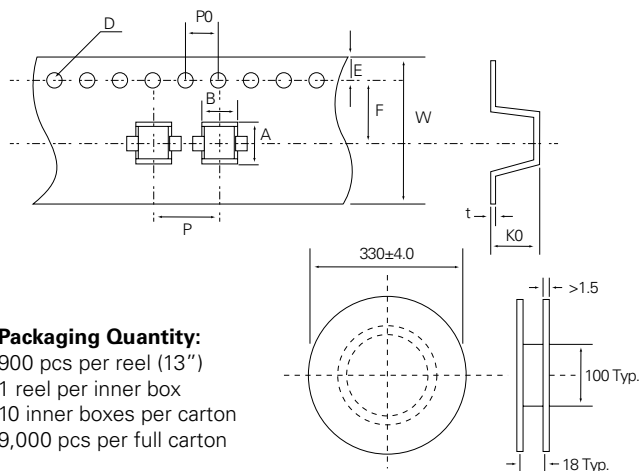


Taping and Reel Specifications

Taping

Unit = mm

Item	Spec	Item	Spec
P	12.0±0.1	D	Ø1.55±0.05
P0	4.0±0.1	W	16.0±0.3
A	5.4±0.1	K0	5.4±0.1
B	4.6±0.1	t	0.5±0.05



Packaging Quantity:
900 pcs per reel (13")
1 reel per inner box
10 inner boxes per carton
9,000 pcs per full carton

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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